

# DMC9610E

## Silicon NPN epitaxial planar type

For digital circuits

DMC5610E in SSMini5 type package

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Basic Part Number

Dual DRC2144W (Common emitter)

### ■ Packaging

DMC9610E0R Embossed type (Thermo-compression sealing): 8000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	50	V
Collector-emitter voltage (Base open)	$V_{CEO}$	50	V
Collector current	$I_C$	100	mA
Total power dissipation	$P_T$	125	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu\text{A}, I_E = 0$	50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 50 \text{ V}, I_E = 0$			0.1	$\mu\text{A}$
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 50 \text{ V}, I_B = 0$			0.5	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_C = 0$			0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 10 \text{ V}, I_C = 5 \text{ mA}$	60			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$			0.25	V
Input voltage (ON)	$V_{I(on)}$	$V_{CE} = 0.2 \text{ V}, I_C = 5 \text{ mA}$	4.4			V
Input voltage (OFF)	$V_{I(off)}$	$V_{CE} = 5 \text{ V}, I_C = 100 \mu\text{A}$			1.2	V
Input resistance	$R_1$		-30%	47	+30%	$\text{k}\Omega$
Resistance ratio	$R_1 / R_2$		1.70	2.14	2.60	—

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

### ■ Package

#### • Code

SSMini5-F4-B

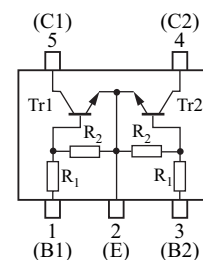
Package dimension clicks here.→

#### • Pin Name

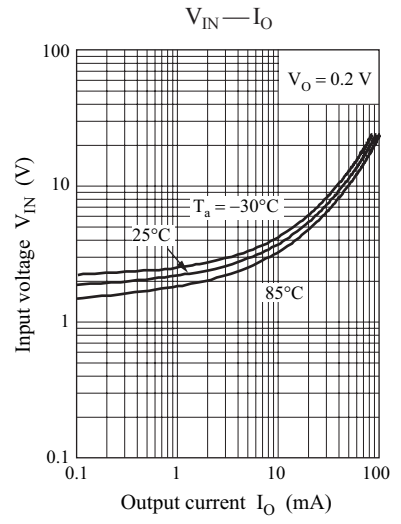
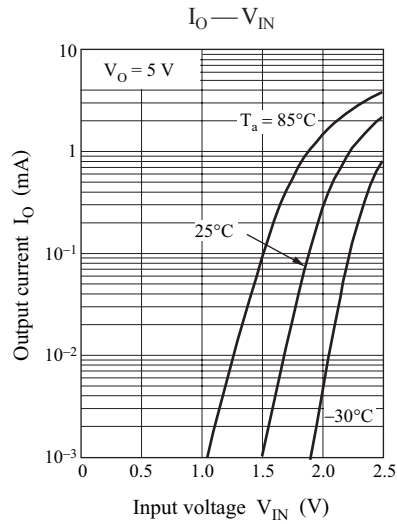
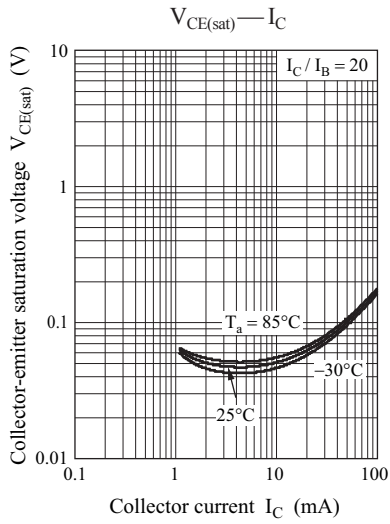
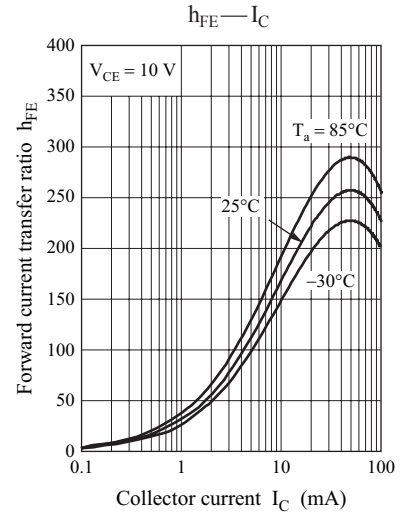
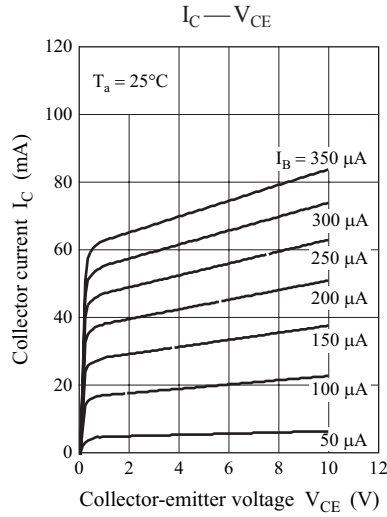
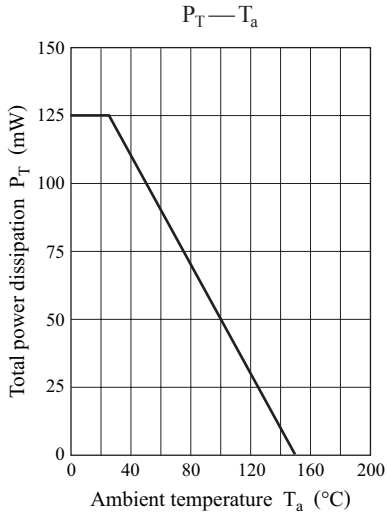
- 1: Base (Tr1)                      4: Collector (Tr2)
- 2: Emitter (Common)            5: Collector (Tr1)
- 3: Base (Tr2)

### ■ Marking Symbol: R1

### ■ Internal Connection



Resistance value	$R_1$	47	$\text{k}\Omega$
	$R_2$	22	



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